

RELIABILITY REPORT
FOR
MAX3867ECM
PLASTIC ENCAPSULATED DEVICES

July 5, 2002

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Reviewed by

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Conclusion

The MAX3867 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3867 is a complete, single +3.3V laser driver for SDH/SONET applications up to 2.5Gbps. The device accepts differential PECL data and clock inputs and provides bias and modulation currents for driving a laser. The synchronizing input latch can be bypassed if a clock signal is not available.

An automatic power control (APC) feedback loop is incorporated to maintain a constant average optical power over temperature and lifetime. The wide modulation current range of 5mA to 60mA and bias current of 1mA to 100mA are easy to program, making this product ideal for use in various SDH/SONET applications.

The MAX3867 also provides enable control, a programmable slow-start circuit to set the laser turn-on delay, and a failure-monitor output to indicate when the APC loop is unable to maintain the average optical power. The MAX3867 is available in a small 48-pin TQFP package as well as dice.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Supply Voltage, VCC	-0.5V to +7.0V
Current into BIAS	-20mA to +150mA
Current into OUT+, OUT-	-20mA to +100mA
Current into MD	-5mA to +5mA
Voltage at DATA+, DATA-, CLK+, CLK-, ENABLE, LATCH, FAIL, SLWSTRT	-0.5V to (VCC + 0.5V)
Voltage at APCFILT, CAPC, MODSET, BIASMAX, APCSET	-0.5V to +3.0V
Voltage at OUT+, OUT-	+1.5V to (VCC + 1.5V)
Voltage at BIAS	+1.0V to (VCC + 0.5V)
Current into FAIL	-10mA to +30mA
Storage Temp.	-65°C to +165°C
Operating Junction Temperature Range	-55°C to +150°C
Lead Temp. (10 sec.)	+300°C
Continuous Power Dissipation (TA = +85°C)	
48-Pin TQFP	1354mW
Derates above +85°C	
48-Pin TQFP	20.8mW/°C

II. Manufacturing Information

A. Description/Function:	+3.3V, 2.5Gbps SDH/SONET Laser Driver with Automatic Power Control
B. Process:	GST2 (High-Speed Double Poly-Silicon Bipolar Process)
C. Number of Device Transistors:	1561
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Malaysia
F. Date of Initial Production:	July, 1998

III. Packaging Information

A. Package Type:	48-Pin TQFP
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1.2 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-7001-0300
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	70 x 83 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Poly / Au
D. Backside Metallization:	None
E. Minimum Metal Width:	1.4 microns (as drawn)
F. Minimum Metal Spacing:	1.4 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord	(Reliability Lab Manager)
Bryan Preeshl	(Executive Director of QA)
Kenneth Huening	(Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 9823 \times 60 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

└─ Thermal acceleration factor assuming a 0.8eV activation energy

$$\lambda = 9.19 \times 10^{-9}$$

$$\lambda = 9.19 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure the reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on lots exceeding this level. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The HF22 die type has been found to have all pins able to withstand a transient pulse of $\pm 500\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 50\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX3867ECM

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality		60	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	TQFP	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process Data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

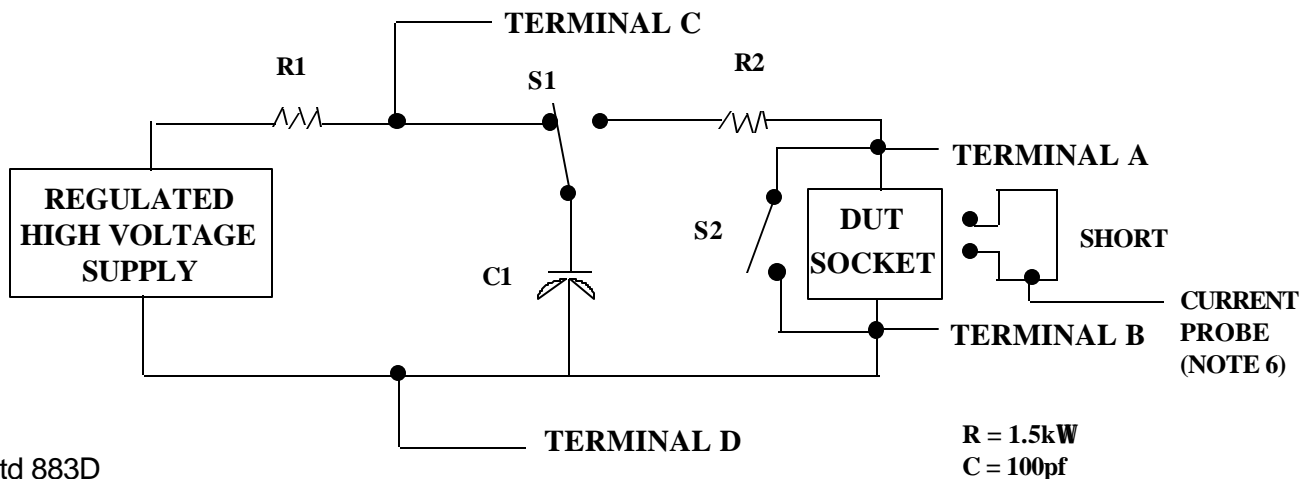
2/ No connects are not to be tested.

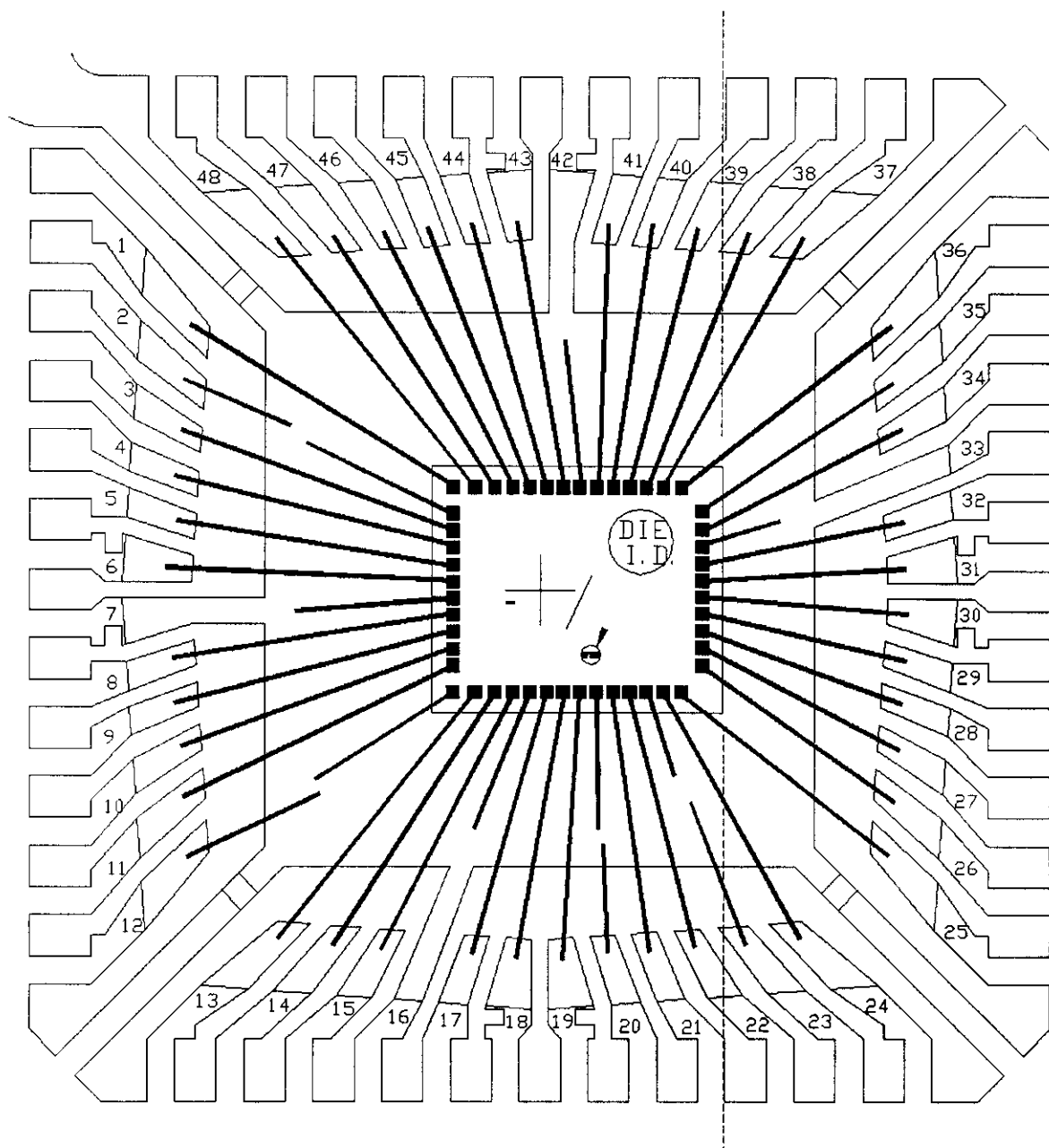
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





OFFSET DIE PLACEMENT TO RIGHT AS SHOWN.

DOWN BOND LENGTHS FROM DIE TO PAD NEAR LEADS 23 + 33
ARE CRITICAL: TARGET 25 MILS MAX. ALL OTHERS CAN BE 40-45 MILS.

PKG. CODE: C48-4F

CAV./PAD SIZE:
157x157

PKG.
DESIGN

APPROVALS

DATE

MAXIM

BUILDSHEET NUMBER:
05-7001-0300

REV.:
B